L Number	Hits	Search Text	DB	Time stamp
1	106	interconnect\$4 and ((first adj (etch\$4 or clean\$4 or treat\$4 or anneal\$4)) same (copper or Cu)) and ((second adj (etch\$4 or clean\$4 or treat\$4 or anneal\$4)) same (copper or Cu)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 13:06
2	748421	interconnect\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 13:06
3	40	interconnect\$4 and ((first adj (etch\$4 or clean\$4 or treat\$4 or anneal\$4)) with (copper or Cu)) and ((second adj (etch\$4 or clean\$4 or treat\$4 or anneal\$4)) with (copper or Cu)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 13:41
4	6	interconnect\$4 and ((first adj (anneal\$4 or treat\$4)) with (copper or Cu)) and ((second adj (treat\$4 or anneal\$4)) with (copper or Cu)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 13:43